

ABSTRACT OF THE INVENTION

An improved structure of a uniform thermal conductive heat dissipation device, having a thermal conductor and a plurality of heat pipes. The thermal conductor includes a convex body member, on which a plurality of parallel connecting parts is formed to allow the heat pipes embedded therein. Each of the heat pipes has a wick structure and a working fluid therein. Each heat pipe has a heat absorbing portion and a heat dissipation portion. The heat absorption portion is closely in contact with the thermal conductor. Thereby, each of the heat is subject to the same amount of heat to result in a uniform thermal conduction and dissipation effect.